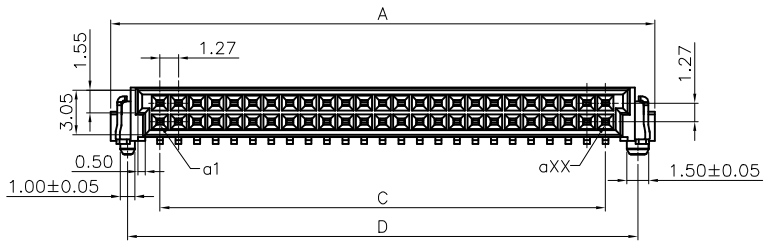
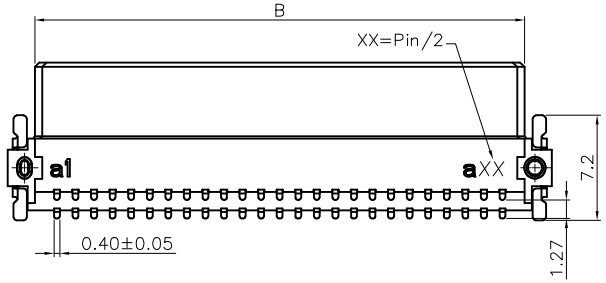
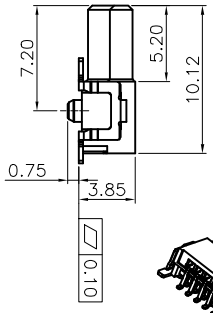
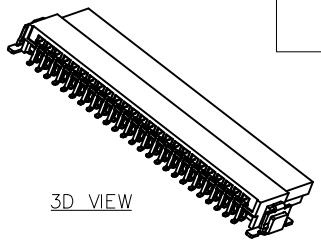
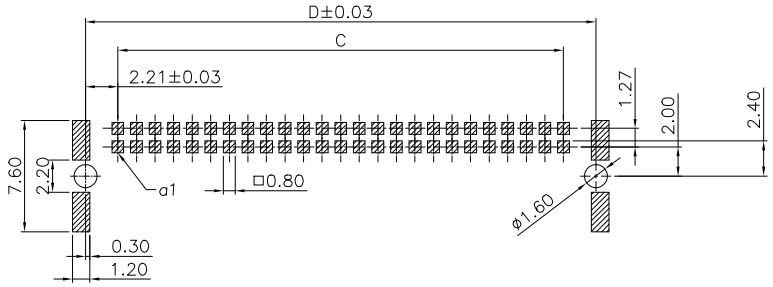
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
1			INITIAL RELEASE	2020.02.15	Yy_D











RECOMMENDED PCB LAYOUT(TOLERANCE: ±0.05)

1. MATERIAL
   1.1 INSULATOR: LCP, UL94V-0, BLACK COLOR.
   1.2 CONTACT: COPPER ALLOY, GOLD PLATED(SEE ORDER INFORMATION)
   IN CONTACT AREA, 100u" MIN. MATTE-TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
   1.3 LATCH: COPPER ALLOY, 100u" MIN. MATTE-TIN PLATED, 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. SPECIFICATIONS:
   2.1 CURRENT RATING: 1.7A MAX.
   2.2 WITHSTANDING VOLTAGE: 500V AC/MINUTE.
   2.3 INSULATION RESISTANCE: 10000M OHMS MIN. DC 500V.
   2.4 CONTACT RESISTANCE: 25mΩ MAX.
   2.5 OPERATING TEMPERATURE: -55'C ~ +125'C.
   2.6 DURABILITY: 500 CYCLES.

5704BG-010R*0***R-**

- R: ACQUIESCENT
- PIN:
  12: 12PIN
  .....
  80: 80PIN
- 0: BLACK
- CONTACTS PLATEING:
  1: Au G/F 2: Au 5u"
  3: Au 15u" 4: Au 30u"
- R:RoHS
  H:HALOGEN-FREE
- WTB

NO.of Pins	A	B	C	D
80	56.28	52.55	49.53	53.95
68	48.66	44.93	41.91	46.33
50	37.23	33.50	30.48	34.90
40	30.88	27.15	24.13	28.55
32	25.80	22.07	19.05	23.47
26	21.99	18.26	15.24	19.66
20	18.18	14.45	11.43	15.85
16	15.64	11.91	8.89	13.31
12	13.10	9.37	6.35	10.77

DIM	TOL
X.	±0.35
.X	±0.30
.XX	±0.25

DIM	TOL
X.	±2'

DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING		DATE	TITLE: WTB 1.27PH 3.85H SMT CONN
DRAW NO. ***	DESIGN:	Yy_D	2020.02.15 P/N:SEE TABLE
	CHECK:		SHEET: 1/2
REV. 1	APPROVAL:		SCALE: 1:1 UNIT: mm